



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of "Quality Parts,Customers Priority,Honest Operation,and Considerate Service",our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



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Product Description

Laird Tflex™ HD300 is a 2.7 W/mK gap filler material in Laird's high deflection line of products. Tflex™ HD300 is an excellent choice when wide manufacturing tolerances occur as variable gaps can be filled with Tflex™ HD300 while generating minimal board and component stress. Laird's unique manufacturing capabilities, and filler and resin knowledge result in this unique product designed with customer applications in mind.

Tflex™ HD300 material exhibits excellent surface wetting characteristics and high deflection properties ensuring low contact resistances and providing an overall lower total thermal resistance.

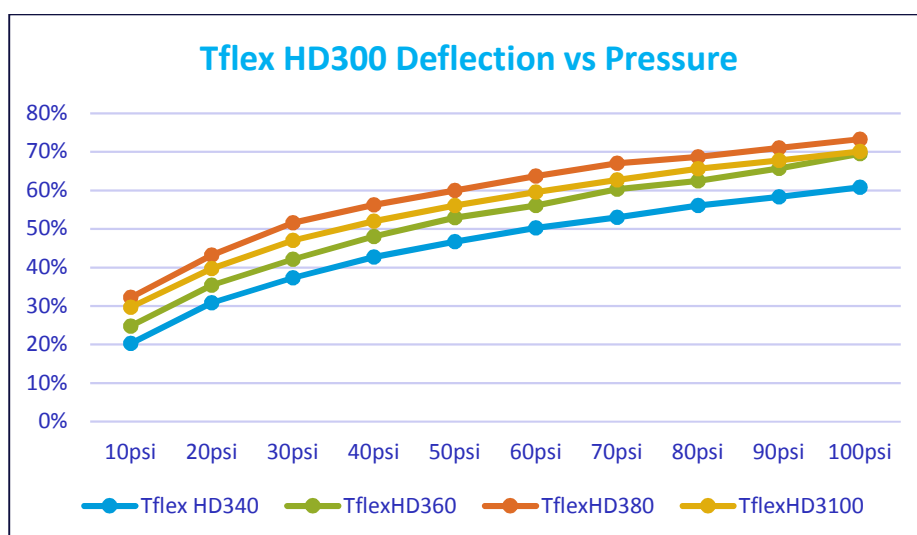
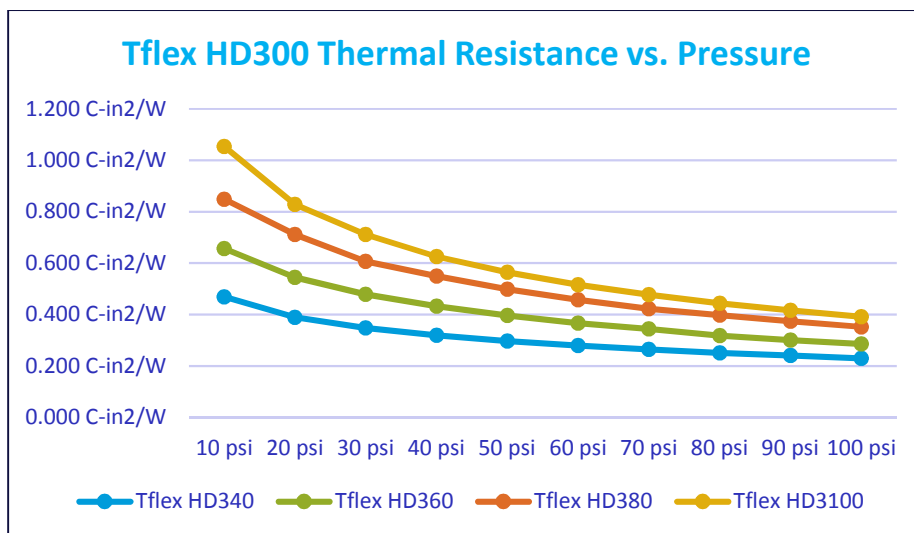
Tflex™ HD300 is provided in thickness from 0.5mm (.020") up to 5mm (.200") in 0.5mm (.020") increments as standard. In addition, Laird can provide Tflex™ HD300 in multiple converted formats through approved converters and distribution networks.

FEATURES AND BENEFITS

- 2.7 W/m K thermal conductivity
- Low pressure versus deflection characteristics
- Excellent surface wetting for low contact resistance
- Minimizes board and component stress.
- Large tolerance applications
- RoHS and REACH compliant

SPECIFICATIONS

TYPICAL PROPERTIES	VALUE	TEST METHOD
Construction & Composition	Ceramic filled silicone sheet	N/A
Color	Pink	Visual
Thickness Range	0.50mm (0.020") 5.0mm (0.20")	N/A
Thermal Conductivity (W/mK)	2.7	ASTM D5470
Density (g/cc)	3.1	Helium Pycnometer
Hardness (Shore 00)	38	ASTM D2240
Outgassing TML (weight %)	0.39	ASTM E595
Outgassing CVM (weight %)	0.10	ASTM E595
Temperature Range	-40°C to 200°C	Laird Test Method
Rth@ 40 mils, 10 psi	0.573°C-in ² /W	ASTM D5470 (Modified)
Dielectric Constant @ 1 MHz	6.62	ASTM D150
UL Flammability Rating	V-0	UL-94
Volume Resistivity	1.2x 10 ¹⁴	ASTM D257



AVAILABILITY

STANDARD THICKNESSES

- 0.5mm (0.020") to 5.0mm (0.200") thick material available in 0.25mm (0.010") increments
- Available in standard sheet sizes of 18" x 18" and 9" x 9" or custom die cut parts

OPTIONS

- DC1 – eliminate tack from one side

PART NUMBER SYSTEM

Tflex™ indicates Laird elastomeric thermal gap filler product line. HD3xxx indicates Tflex HD300 product line with thickness in mils (0.001")

EXAMPLES:

- Tflex™ HD340 = 0.040" thick Tflex™ HD300 material
- Tflex™ HD3100DC1 = 0.10" thick Tflex™ HD300 material with DC1 option

A15293-00 Tflex HD300 DS 071017